

April 2013

# MOC205M, MOC206M, MOC207M Small Outline Optocouplers Transistor Output

#### **Features**

- U.L. Recognized (File #E90700, Volume 2)
- VDE Recognized (File #136616) (add option "V" for VDE approval, i.e, MOC205VM)
- Closely Matched Current Transfer Ratios
- Convenient Plastic SOIC-8 Surface Mountable Package Style
- Minimum BV<sub>CEO</sub> of 70 V Guaranteed
- Standard SOIC-8 Footprint, with 0.050" Lead Spacing
- High Input-Output Isolation of 2500 V<sub>AC(rms)</sub> Guaranteed

# **Applications**

- Feedback Control Circuits
- Interfacing and Coupling Systems of Different Potentials and Impedances
- General Purpose Switching Circuits
- Monitor and Detection Circuits

# **Description**

These devices consist of a gallium arsenide infrared emitting diode optically coupled to a monolithic silicon phototransistor detector, in a surface mountable, small outline, plastic package. They are ideally suited for high density applications, and eliminate the need for throughthe-board mounting.

#### **Schematic**

# ANODE 1 CATHODE 2 N/C 3 R/C 4 BASE COLLECTOR 5 EMITTER

Figure 1. Schematic

# **Package Outline**

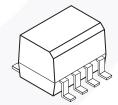


Figure 2. Package Outline

# **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.  $T_A = 25^{\circ}C$  unless otherwise specified.

Symbol	Rating	Value	Unit
Emitter			
I <sub>F</sub>	Forward Current – Continuous	60	mA
I <sub>F</sub> (pk)	Forward Current – Peak (PW = 100 µs, 120 pps)	1.0	А
V <sub>R</sub>	Reverse Voltage	6.0	V
P <sub>D</sub>	LED Power Dissipation @ T <sub>A</sub> = 25°C	90	mW
	Derate above 25°C	0.8	mW/°C
Detector			
V <sub>CEO</sub>	Collector-Emitter Voltage	70	V
V <sub>ECO</sub>	Emitter-Collector Voltage	7.0	V
V <sub>CBO</sub>	Collector-Base Voltage	70	V
I <sub>C</sub>	Collector Current-Continuous	150	mA
P <sub>D</sub>	Detector Power Dissipation @ T <sub>A</sub> = 25°C	150	mW
	Derate above 25°C	1.76	mW/°C
Total Device			
V <sub>ISO</sub>	Input-Output Isolation Voltage (f = 60 Hz, t = 1 minute) <sup>(1)(2)(3)</sup>	2500	Vac(rms)
P <sub>D</sub>	Total Device Power Dissipation @ T <sub>A</sub> = 25°C	250	mW
	Derate above 25°C	2.94	mW/°C
T <sub>A</sub>	Ambient Operating Temperature Range	-40 to +100	°C
T <sub>stg</sub>	Storage Temperature Range	-40 to +150	°C

#### Notes:

- 1. Isolation Surge Voltage,  $V_{ISO}$ , is an internal device dielectric breakdown rating.
- 2. For this test, pins 1 and 2 are common and pins 5, 6 and 7 are common.
- 3.  $V_{ISO}$  rating of 2500  $V_{AC(rms)}$  for t = 1 minute is equivalent to a rating of 3,000  $V_{AC(rms)}$  for t = 1 second

#### **Electrical Characteristics**

 $T_A = 25^{\circ}C$  unless otherwise specified.

Symbol	Parameter	Test Conditions	Min.	Typ.*	Max.	Unit
Emitter						
V <sub>F</sub>	Input Forward Voltage	I <sub>F</sub> = 10 mA		1.15	1.5	V
I <sub>R</sub>	Reverse Leakage Current	V <sub>R</sub> = 6.0 V		0.001	100	μΑ
C <sub>IN</sub>	Input Capacitance			18		pF
DETECTO	OR .					
I <sub>CEO1</sub>	Collector-Emitter Dark Current	V <sub>CE</sub> = 10 V, T <sub>A</sub> = 25°C V <sub>CE</sub> = 10 V, T <sub>A</sub> = 100°C		1.0 1.0	50	nΑ μΑ
BV <sub>CEO</sub>	Collector-Emitter Breakdown Voltage	I <sub>C</sub> = 100 μA	70	100		V
BV <sub>ECO</sub>	Emitter-Collector Breakdown Voltage	I <sub>E</sub> = 100 μA	7.0	10		V
C <sub>CE</sub>	Collector-Emitter Capacitance	f = 1.0 MHz, V <sub>CE</sub> = 0		7.0		pF
COUPLE	D					
CTR	Collector-Output Current <sup>(4)</sup> MOC205M MOC206M MOC207M	$I_F = 10 \text{ mA}, V_{CE} = 10 \text{ V}$	40 63 100		80 125 200	%
V <sub>ISO</sub>	Isolation Surge Voltage <sup>(1)(2)(3)</sup>	f = 60 Hz AC Peak, t = 1 minute	2500			Vac(rms)
R <sub>ISO</sub>	Isolation Resistance <sup>(2)</sup>	V = 500 V	10 <sup>11</sup>			Ω
V <sub>CE (sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 2 \text{ mA}, I_F = 10 \text{ mA}$			0.4	V
C <sub>ISO</sub>	Isolation Capacitance <sup>(2)</sup>	V = 0 V, f = 1 MHz		0.2		pF
t <sub>on</sub>	Turn-On Time	$I_C = 2.0 \text{ mA}, V_{CC} = 10 \text{ V},$ $R_L = 100 \Omega \text{ (Fig. 12)}$		7.5		μѕ
t <sub>off</sub>	Turn-Off Time	$I_C = 2.0 \text{ mA}, V_{CC} = 10 \text{ V},$ $R_L = 100 \Omega \text{ (Fig. 12)}$		5.7		μs
t <sub>r</sub>	Rise Time	$I_{C}$ = 2.0 mA, $V_{CC}$ = 10 V, $R_{L}$ = 100 $\Omega$ (Fig. 12)		3.2		μѕ
t <sub>f</sub>	Fall Time	$I_C = 2.0 \text{ mA}, V_{CC} = 10 \text{ V},$ $R_L = 100 \Omega \text{ (Fig. 12)}$		4.7		μs

<sup>\*</sup>Typical values at T<sub>A</sub> = 25°C

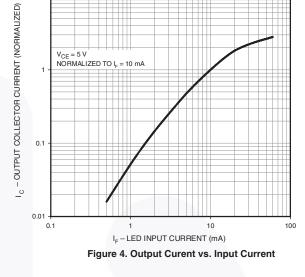
#### Notes

- 1. Isolation Surge Voltage,  $V_{\mbox{\scriptsize ISO}}$ , is an internal device dielectric breakdown rating.
- 2. For this test, pins 1 and 2 are common and pins 5, 6 and 7 are common.
- 3.  $V_{ISO}$  rating of 2500  $V_{AC(rms)}$  for t = 1 minute is equivalent to a rating of 3,000  $V_{AC(rms)}$  for t = 1 second.
- 4. Current Transfer Ratio (CTR) =  $I_C/I_F \times 100\%$ .

# Typical Performance Curves 1.8 1.7 (v) 399 1.5 1.6 1.7 T<sub>A</sub> = -55°C T<sub>A</sub> = 25°C T<sub>A</sub> = 25°C

 $\label{eq:lemma} I_F-\text{LED FORWARD CURRENT (mA)}$  Figure 3. LED Forward Voltage vs. Forward Current

1.0



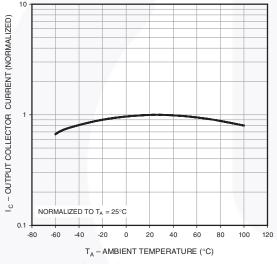


Figure 5. Output Current vs. Ambient Temperature

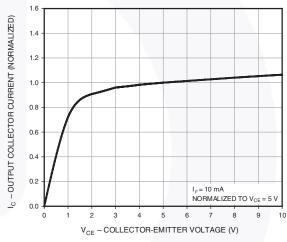
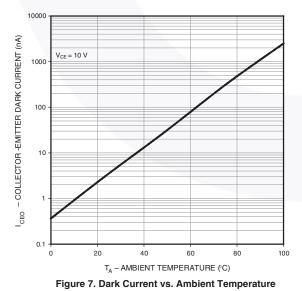


Figure 6. Output Current vs. Collector-Emitter Voltage



1.0 0.9  $I_F = 20 \text{ mA}$ 0.8 0.7  $I_F = 10 \text{ mA}$ 0.6 NORMALIZED CTR 0.5  $I_E = 5 \text{ mA}$ 0.4 0.3 0.2  $V_{CE} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$ Normalized to: CTR at R<sub>BE</sub> = Open 0.1 10  $R_{\mbox{\footnotesize{BE}}}$  -BASE RESISTANCE (k $\Omega$ )

Figure 8. CTR vs. RBE (Unsaturated)

# Typical Performance Curves (Continued)

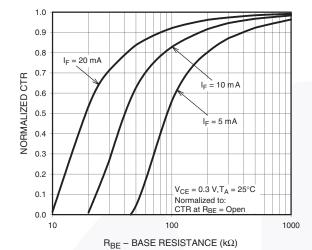


Figure 9. CTR vs. RBE (Saturated)

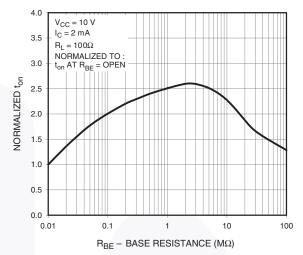


Figure 10. Normalized ton vs. RBE

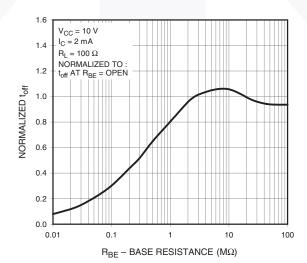


Figure 11. Normalized toff vs. RBE

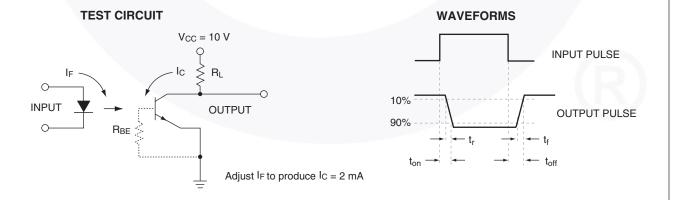
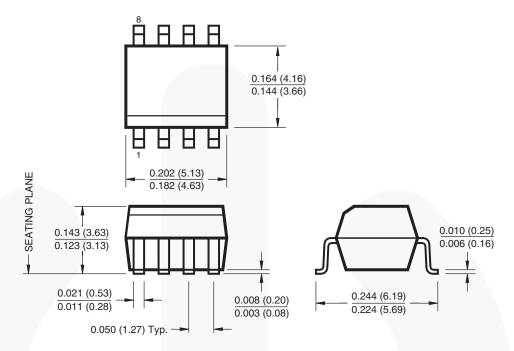


Figure 12. Switching Time Test Circuit and Waveforms

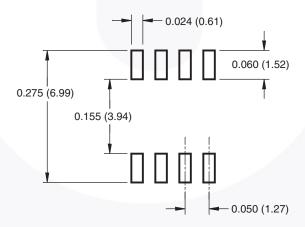
## **Package Dimensions**

#### 8-pin SOIC Surface Mount



Lead Coplanarity: 0.004 (0.10) MAX

#### **Recommended Pad Layout**



Dimensions in inches (mm).

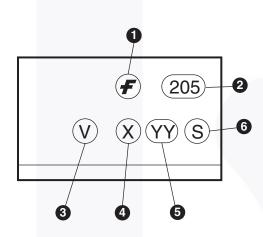
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# **Ordering Information**

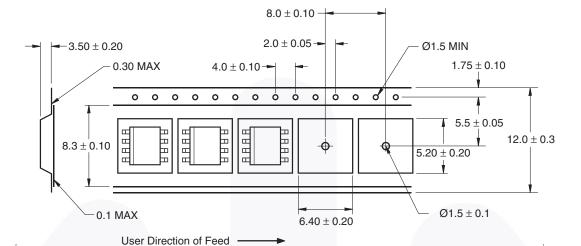
Option	Order Entry Identifier	Description	
V	V	VDE 0884	
R2	R2	Tape and reel (2500 units per reel)	
R2V	R2V	VDE 0884, Tape and reel (2500 units per reel)	

# **Marking Information**



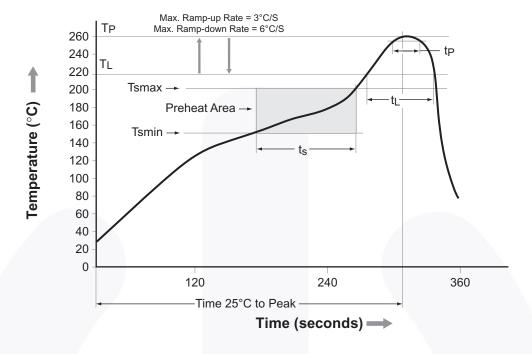
Defini	tions	
1	Fairchild logo	
2	Device number	
3	VDE mark (Note: Only appears on parts ordered with VDE option – See order entry table)	
4	One digit year code, e.g., '8'	
5	Two digit work week ranging from '01' to '53'	
6	Assembly package code	

# **Carrier Tape Specifications**



Dimensions in mm

### **Reflow Profile**



Profile Freature	Pb-Free Assembly Profile
Temperature Minimum (Tsmin)	150°C
Temperature Maximum (Tsmax)	200°C
Time (t <sub>S</sub> ) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t <sub>L</sub> to t <sub>P</sub> )	3°C/second maximum
Liquidous Temperature (T <sub>L</sub> )	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second maximum
Time 25°C to Peak Temperature	8 minutes maximum





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